

IN THE CLAIMS:

A listing of claims 1 through 3 is presented below. None of the claims have been amended herein. These claims have been entered herein for convenience only.

1. (Original) A semiconductor die, comprising:  
a rectangular body having an active surface and a longitudinal centerline; and  
a plurality of bond pads disposed adjacent the longitudinal centerline, wherein the plurality of bond pads are arranged in at least one longitudinal row comprising at least two longitudinally adjacent groups of bond pads separated by a greater space than a space between bond pads within a group.
2. (Original) The semiconductor die of claim 1, wherein the at least two longitudinally adjacent groups of bond pads consists of two longitudinally adjacent groups.
3. (Original) The semiconductor die of claim 1, wherein the at least one longitudinal row comprises two longitudinal rows flanking the longitudinal centerline.